

**PI4ULS3V204**
**4-Bit Bi-directional Level Shifter for open-drain and Push-Pull Application**
**Features**

- ➔  $V_{CCA}$  can be Less than, Greater than or Equal to  $V_{CCB}$
- ➔ 1.1V to 3.6V on A Port and 1.1V to 3.6V on B Port
- ➔ High-Speed with 24 Mb/s Data Rate for push-pull application
- ➔ High-Speed with 2 Mb/s Data Rate for open-drain application
- ➔ No Direction-Control Signal Needed
- ➔ Low Bit-to-Bit Skew
- ➔ Non-preferential Power-up Sequencing
- ➔ ESD protection exceeds 8000V HBM per JESD22-A114
- ➔ Integrated 10 k $\Omega$  Pull-up Resistors
- ➔ Package: TSSOP-14, TQFN3.5x3.5-14, CSP-12

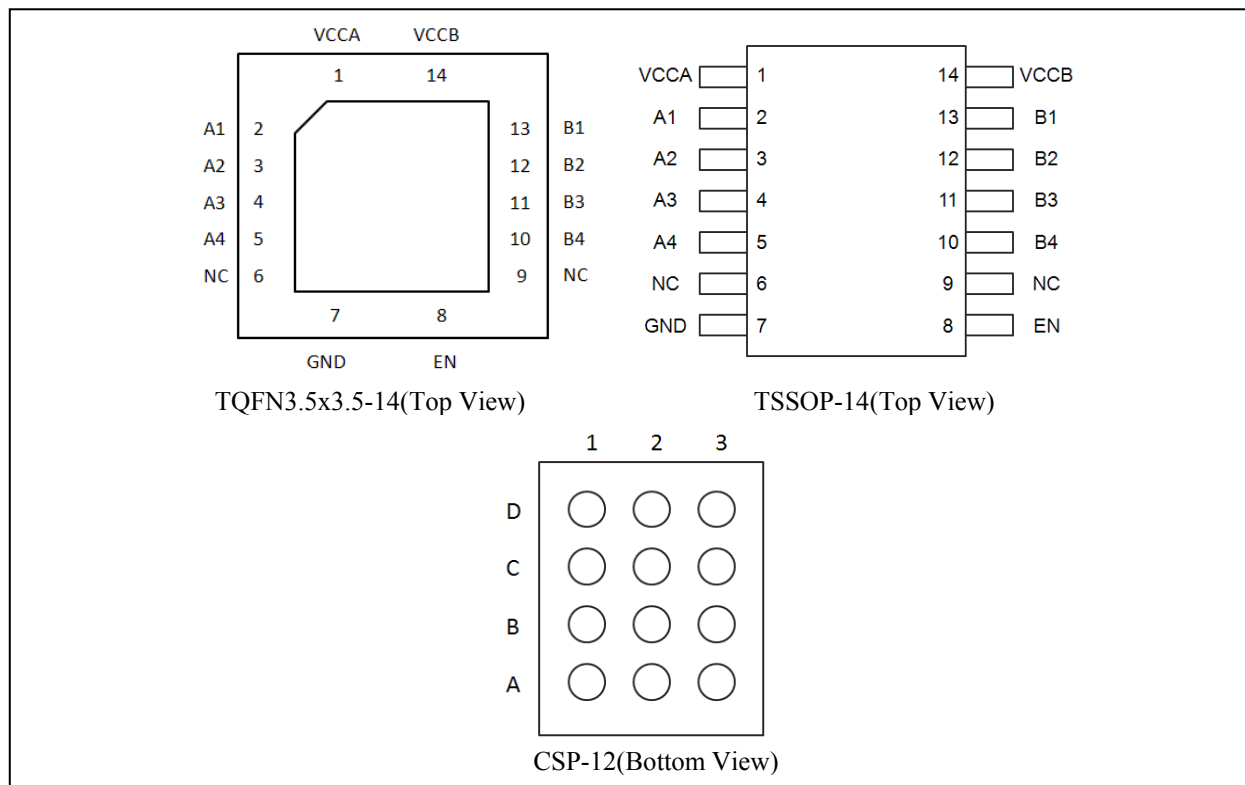
**Applications**

- ➔ I2C, SMBus, MDIO
- ➔ Low Voltage ASIC Level Translation
- ➔ Mobile Phones, PDAs, Camera

**Description**

The PI4ULS3V204 is a 4-bit configurable dual supply bidirectional auto sensing translator that does not require a directional control pin. The A and B ports are designed to track two different power supply rails,  $V_{CCA}$  and  $V_{CCB}$  respectively. Both the  $V_{CCA}$  and  $V_{CCB}$  supply rails are configurable from 1.1V to 3.6V. This allows voltage logic signals on the  $V_{CCA}$  side to be translated into lower, higher or equal value voltage logic signals on the  $V_{CCB}$  side, and vice-versa.

The translator has integrated 10 k $\Omega$  pull-up resistors on the I/O lines. The integrated pull-up resistors are used to pull-up the I/O lines to either  $V_{CCA}$  or  $V_{CCB}$ . The PI4ULS3V204 is an excellent match for open-drain applications such as the I2C communication bus.

**Pin Configuration**


## Block Diagram

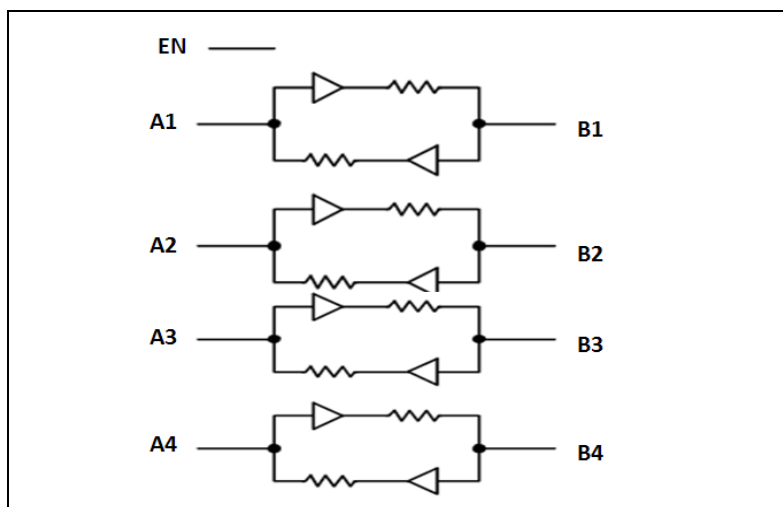


Figure 1: Block Diagram

## Maximum Ratings

Storage Temperature.....	-65°C to +150°C
DC Supply Voltage port B .....	-0.3V to +5.5V
DC Supply Voltage port A.....	-0.3V to +5.5V
Vi(A) referenced DC Input / Output Voltage.....	-0.3V to +5.5V
Vi(B) referenced DC Input / Output Voltage.....	-0.3V to +5.5V
Enable Control Pin DC Input Voltage.....	-0.3V to +5.5V
Short circuit duration (I/O to GND) .....	40mA

### Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

## Pin Description

Pin No TSSOP	Pin No TQFN	Pin No CSP	Pin Name	Type	Description
1	1	B2	V <sub>CCA</sub>	Power	A-port supply voltage. 1.1V ≤ V <sub>CCA</sub> ≤ 3.6 V
2	2	A3	A1	I/O	Input/output A. Referenced to V <sub>CCA</sub> .
3	3	B3	A2	I/O	Input/output A. Referenced to V <sub>CCA</sub>
4	4	C3	A3	I/O	Input/output A. Referenced to V <sub>CCA</sub>
5	5	D3	A4	I/O	Input/output A. Referenced to V <sub>CCA</sub>
7	7	D2	GND	GND	Ground.
8	8	C2	EN	Input	Output enable (active High). Pull EN low to place all outputs in 3-state mode.
10	10	D1	B4	I/O	Input/output B. Referenced to V <sub>CCB</sub>
11	11	C1	B3	I/O	Input/output B. Referenced to V <sub>CCB</sub>
12	12	B1	B2	I/O	Input/output B. Referenced to V <sub>CCB</sub>
13	13	A1	B1	I/O	Input/output B. Referenced to V <sub>CCB</sub>
14	14	A2	V <sub>CCB</sub>	Power	B-port supply voltage. 1.1 V ≤ V <sub>CCB</sub> ≤ 3.6V
6, 9	6, 9	/	NC	NC	Not Connect

## Recommended Operation Conditions

Symbol	Parameter	Min	Typ	Max	Unit
$V_{CCA}$	$V_{CCA}$ Positive DC Supply Voltage	1.1	-	3.6	V
$V_{CCB}$	$V_{CCB}$ Positive DC Supply Voltage	1.1	-	3.6	V
$V_{EN}$	Enable Control Pin Voltage	GND	-	3.6	V
$V_{IO}$	I/O Pin Voltage	GND	-	3.6	V
$\Delta t / \Delta V$	Input transition rise or fall time	-	-	10	ns/V
$T_A$	Operating Temperature Range	-40	-	+85	°C

## DC Electrical Characteristics

Unless otherwise specified,  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ ,  $1.1\text{V} \leq V_{CC} \leq 3.6\text{V}$

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$V_{IHB}$	B port Input HIGH Voltage	$2.3\text{V} \leq V_{CC(B)} \leq 3.6\text{V}$	$V_{CCB} - 0.4$	-	-	V
		$1.5\text{V} \leq V_{CC(B)} < 2.3\text{V}$	$V_{CCB} - 0.2$			V
		$1.1\text{V} \leq V_{CC(B)} < 1.5\text{V}$	$V_{CCB} - 0.1$			V
$V_{ILB}$	B port Input LOW Voltage			-	0.15	V
$V_{IHA}$	A port Input HIGH Voltage	$2.3\text{V} \leq V_{CC(A)} \leq 3.6\text{V}$	$V_{CCA} - 0.4$			V
		$1.5\text{V} \leq V_{CC(A)} < 2.3\text{V}$	$V_{CCA} - 0.2$			V
		$1.1\text{V} \leq V_{CC(A)} < 1.5\text{V}$	$V_{CCA} - 0.1$			V
$V_{ILA}$	A port Input LOW Voltage	-	-	-	0.15	V
$V_{IH(EN)}$	Control Pin Input HIGH Voltage	$1.5\text{V} < V_{CC(A)} \leq 3.6\text{V}$	$0.65 * V_{CCA}$	-	-	V
		$1.1\text{V} \leq V_{CC(A)} \leq 1.5\text{V}$	$0.6 * V_{CCA}$			V
$V_{IL(EN)}$	Control Pin Input LOW Voltage	$1.5\text{V} < V_{CC(A)} \leq 3.6\text{V}$	-	-	$0.35 * V_{CCA}$	V
		$1.1\text{V} \leq V_{CC(A)} \leq 1.5\text{V}$			$0.2 * V_{CCA}$	V
$V_{OHB}$	B port Output HIGH Voltage	B port source current = -20 $\mu\text{A}$	$0.8 * V_{CCB}$	-	-	V
$V_{OLB}$	B port Output LOW Voltage	B port sink current = 1 mA	-	-	0.4	V
$V_{OHA}$	A port Output HIGH Voltage	A port source current = -20 $\mu\text{A}$	$0.8 * V_{CCA}$	-	-	V
$V_{OLA}$	A port Output LOW Voltage	A port sink current = 1 mA	-	-	0.4	V
$I_{CCB}$	$V_{CCB}$ Supply Current	$V_I = V_{CCI};$ $I_O = 0\text{A};$ EN= Low or High	$V_{CC(A)} = 1.1\text{V to } 3.6\text{V},$ $V_{CC(B)} = 1.1\text{V to } 3.6\text{V}$	-	1.0	3 $\mu\text{A}$
			$V_{CCA} = 1.1\text{V}, V_{CCB} = 1.8\text{V}$	-	0.6	2 $\mu\text{A}$
			$V_{CCA} = 1.8\text{V}, V_{CCB} = 3.3\text{V}$	-	0.7	2 $\mu\text{A}$
			$V_{CC(A)} = 3.6\text{V}, V_{CC(B)} = 0\text{V}$	-		1 $\mu\text{A}$
			$V_{CC(A)} = 0\text{V}, V_{CC(B)} = 3.6\text{V}$	-		1 $\mu\text{A}$
$I_{CCA}$	$V_{CCA}$ Supply Current	$V_I = V_{CCI};$ $I_O = 0\text{A};$ EN= Low or High	$V_{CC(A)} = 1.1\text{V to } 3.6\text{V},$ $V_{CC(B)} = 1.1\text{V to } 3.6\text{V}$	-	0.2	1 $\mu\text{A}$
			$V_{CC(A)} = 3.6\text{V}, V_{CC(B)} = 0\text{V}$	-	-	1 $\mu\text{A}$
			$V_{CC(A)} = 0\text{V}, V_{CC(B)} = 3.6\text{V}$	-	-	1 $\mu\text{A}$
$I_{OZ}$	I/O Tri-state Output Mode Leakage Current	-	-	0.1	1.0	$\mu\text{A}$
$I_{I-EN}$	Control pin leakage Current	$V_I = V_{CCI}$ or GND	-	-	1	$\mu\text{A}$
$R_{PU}$	Pull-Up Resistors I/O A and B	-	-	10	-	k $\Omega$
$C_i$	EN	$V_{CC(A)} = 3.3\text{V}, V_{CC(B)} = 3.3\text{V}$	-	-	0.5	pF
$C_{iO}$	A port	$V_{CC(A)} = 3.3\text{V}, V_{CC(B)} = 3.3\text{V}$	-	-	5	pF
	B port	$V_{CC(A)} = 3.3\text{V}, V_{CC(B)} = 3.3\text{V}$	-	-	5	pF

**Note:** All units are production tested at  $T_A = +25^{\circ}\text{C}$ . Limits over the operating temperature range are guaranteed by design.

Typical values are for  $V_{CCB} = +2.8\text{V}$ ,  $V_{CCA} = +1.8\text{V}$  and  $T_A = +25^{\circ}\text{C}$ .

## AC Electrical Characteristics

**Timing Characteristics – Rail-to-Rail Driving Configuration** (I/O test circuits of Figures 2, 3 and 7,  $C_{LOAD} = 15\text{ pF}$ , driver output impedance  $\leq 50\Omega$ ,  $R_{LOAD} = 1\text{ M}\Omega$ ,  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$ , unless otherwise specified)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b><math>V_{CCA} = 1.2V \pm 0.1V</math>, <math>V_{CCB} = 1.8V \pm 0.15V</math></b>						
$t_{RB}$	B port Rise Time	-			20	nS
$t_{FB}$	B port Fall Time	-			25	nS
$t_{RA}$	A port Rise Time	-			20	nS
$t_{FA}$	A port Fall Time	-			20	nS
$t_{EN}$	Enable Time	-			200	nS
$t_{DIS}$	Disable Time	-			200	nS
$t_{PHL-A-B}$	Propagation Delay (Driving A)	-			9	nS
$t_{PLH-A-B}$		-			11	nS
$t_{PHL-B-A}$	Propagation Delay (Driving B)	-			9	nS
$t_{PLH-B-A}$		-			10	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			20	Mbps
<b><math>V_{CCA} = 1.2V \pm 0.1V</math>, <math>V_{CCB} = 2.5V \pm 0.2V</math></b>						
$t_{RB}$	B port Rise Time	-			12	nS
$t_{FB}$	B port Fall Time	-			14	nS
$t_{RA}$	A port Rise Time	-			20	nS
$t_{FA}$	A port Fall Time	-			25	nS
$t_{EN}$	Enable Time	-			200	nS
$t_{DIS}$	Disable Time	-			200	nS
$t_{PHL-A-B}$	Propagation Delay (Driving A)	-			9	nS
$t_{PLH-A-B}$		-			11	nS
$t_{PHL-B-A}$	Propagation Delay (Driving B)	-			9	nS
$t_{PLH-B-A}$		-			10	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			20	Mbps
<b><math>V_{CCA} = 1.2V \pm 0.1V</math>, <math>V_{CCB} = 3.3V \pm 0.3V</math></b>						
$t_{RB}$	B port Rise Time	-			12	nS
$t_{FB}$	B port Fall Time	-			18	nS
$t_{RA}$	A port Rise Time	-			16	nS
$t_{FA}$	A port Fall Time	-			30	nS
$t_{EN}$	Enable Time	-			200	nS
$t_{DIS}$	Disable Time	-			200	nS
$t_{PHL-A-B}$	Propagation Delay (Driving A)	-			8	nS
$t_{PLH-A-B}$		-			11	nS
$t_{PHL-B-A}$	Propagation Delay (Driving B)	-			8	nS
$t_{PLH-B-A}$		-			10	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			20	Mbps

## AC Electrical Characteristics (Cont..)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b><math>V_{CCA} = 1.8V \pm 0.15V</math>, <math>V_{CCB} = 1.2V \pm 0.1V</math></b>						
$t_{RB}$	B port Rise Time	-			25	nS
$t_{FB}$	B port Fall Time	-			25	nS
$t_{RA}$	A port Rise Time	-			14	nS
$t_{FA}$	A port Fall Time	-			25	nS
$t_{EN}$	Enable Time	-			200	nS
$t_{DIS}$	Disable Time	-			200	nS
$t_{PHL-A-B}$	Propagation Delay (Driving A)	-			10	nS
$t_{PLH-A-B}$		-			15	nS
$t_{PHL-B-A}$	Propagation Delay (Driving B)	-			12	nS
$t_{PLH-B-A}$		-			12	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			20	Mbps
<b><math>V_{CCA} = 1.8V \pm 0.15V</math>, <math>V_{CCB} = 2.5V \pm 0.2V</math></b>						
$t_{RB}$	B port Rise Time	-			8	nS
$t_{FB}$	B port Fall Time	-			8	nS
$t_{RA}$	A port Rise Time	-			6	nS
$t_{FA}$	A port Fall Time	-			12	nS
$t_{EN}$	Enable Time	-			200	nS
$t_{DIS}$	Disable Time	-			150	nS
$t_{PHL-A-B}$	Propagation Delay (Driving A)	-			5	nS
$t_{PLH-A-B}$		-			4	nS
$t_{PHL-B-A}$	Propagation Delay (Driving B)	-			4	nS
$t_{PLH-B-A}$		-			4	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			24	Mbps
<b><math>V_{CCA} = 1.8V \pm 0.15V</math>, <math>V_{CCB} = 3.3V \pm 0.3V</math></b>						
$t_{RB}$	B port Rise Time	-			8	nS
$t_{FB}$	B port Fall Time	-			8	nS
$t_{RA}$	A port Rise Time	-			4	nS
$t_{FA}$	A port Fall Time	-			10	nS
$t_{EN}$	Enable Time	-			180	nS
$t_{DIS}$	Disable Time	-			120	nS
$t_{PHL-A-B}$	Propagation Delay (Driving A)	-			6	nS
$t_{PLH-A-B}$		-			4	nS
$t_{PHL-B-A}$	Propagation Delay (Driving B)	-			4	nS
$t_{PLH-B-A}$		-			4	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			24	Mbps

# AC Electrical Characteristics (Cont..)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b><math>V_{CCA} = 2.5V \pm 0.2V</math>, <math>V_{CCB} = 1.2V \pm 0.1V</math></b>						
$t_{RB}$	B port Rise Time	-			25	nS
$t_{FB}$	B port Fall Time	-			30	nS
$t_{RA}$	A port Rise Time	-			12	nS
$t_{FA}$	A port Fall Time	-			30	nS
$t_{EN}$	Enable Time	-			200	nS
$t_{DIS}$	Disable Time	-			180	nS
$t_{PHL-A-B}$	Propagation Delay (Driving A)	-			10	nS
$t_{PLH-A-B}$		-			14	nS
$t_{PHL-B-A}$	Propagation Delay (Driving B)	-			20	nS
$t_{PLH-B-A}$		-			12	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			20	Mbps
<b><math>V_{CCA} = 2.5V \pm 0.2V</math>, <math>V_{CCB} = 1.8V \pm 0.15V</math></b>						
$t_{RB}$	B port Rise Time	-			8	nS
$t_{FB}$	B port Fall Time	-			9	nS
$t_{RA}$	A port Rise Time	-			9	nS
$t_{FA}$	A port Fall Time	-			9	nS
$t_{EN}$	Enable Time	-			200	nS
$t_{DIS}$	Disable Time	-			120	nS
$t_{PHL-A-B}$	Propagation Delay (Driving A)	-			3	nS
$t_{PLH-A-B}$		-			2	nS
$t_{PHL-B-A}$	Propagation Delay (Driving B)	-			5	nS
$t_{PLH-B-A}$		-			5	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			24	Mbps
<b><math>V_{CCA} = 2.5V \pm 0.2V</math>, <math>V_{CCB} = 3.3V \pm 0.3V</math></b>						
$t_{RB}$	B port Rise Time	-			7	nS
$t_{FB}$	B port Fall Time	-			8	nS
$t_{RA}$	A port Rise Time	-			4	nS
$t_{FA}$	A port Fall Time	-			10	nS
$t_{EN}$	Enable Time	-			200	nS
$t_{DIS}$	Disable Time	-			120	nS
$t_{PHL-A-B}$	Propagation Delay (Driving A)	-			3	nS
$t_{PLH-A-B}$		-			5	nS
$t_{PHL-B-A}$	Propagation Delay (Driving B)	-			4	nS
$t_{PLH-B-A}$		-			4	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			24	Mbps

# AC Electrical Characteristics (Cont..)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b><math>V_{CCA} = 3.3V \pm 0.3V</math>, <math>V_{CCB} = 1.2V \pm 0.1V</math></b>						
$t_{RB}$	B port Rise Time	-			26	nS
$t_{FB}$	B port Fall Time	-			32	nS
$t_{RA}$	A port Rise Time	-			12	nS
$t_{FA}$	A port Fall Time	-			40	nS
$t_{EN}$	Enable Time	-			120	nS
$t_{DIS}$	Disable Time	-			300	nS
$t_{PHL-A-B}$	Propagation Delay (Driving A)	-			10	nS
$t_{PLH-A-B}$		-			14	nS
$t_{PHL-B-A}$	Propagation Delay (Driving B)	-			25	nS
$t_{PLH-B-A}$		-			12	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			20	Mbps
<b><math>V_{CCA} = 3.3V \pm 0.3V</math>, <math>V_{CCB} = 1.8V \pm 0.15V</math></b>						
$t_{RB}$	B port Rise Time	-			6	nS
$t_{FB}$	B port Fall Time	-			11	nS
$t_{RA}$	A port Rise Time	-			6	nS
$t_{FA}$	A port Fall Time	-			7	nS
$t_{EN}$	Enable Time	-			120	nS
$t_{DIS}$	Disable Time	-			200	nS
$t_{PHL-A-B}$	Propagation Delay (Driving A)	-			4	nS
$t_{PLH-A-B}$		-			4	nS
$t_{PHL-B-A}$	Propagation Delay (Driving B)	-			5	nS
$t_{PLH-B-A}$		-			5	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			24	Mbps
<b><math>V_{CCA} = 3.3V \pm 0.3V</math>, <math>V_{CCB} = 2.5V \pm 0.2V</math></b>						
$t_{RB}$	B port Rise Time	-			6	nS
$t_{FB}$	B port Fall Time	-			10	nS
$t_{RA}$	A port Rise Time	-			6	nS
$t_{FA}$	A port Fall Time	-			7	nS
$t_{EN}$	Enable Time	-			120	nS
$t_{DIS}$	Disable Time	-			200	nS
$t_{PHL-A-B}$	Propagation Delay (Driving A)	-			4	nS
$t_{PLH-A-B}$		-			4	nS
$t_{PHL-B-A}$	Propagation Delay (Driving B)	-			4	nS
$t_{PLH-B-A}$		-			4	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			24	Mbps

## Timing Characteristics – Open Drain Driving Configuration

( $1.1 \leq V_{CCA} \leq V_{CCB} \leq 3.6V$ ,  $T_A = -40^\circ C$  to  $85^\circ C$ )

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$t_{RB}$	B port Rise Time	-	-	-	300	nS
$t_{FB}$	B port Fall Time	-	-	-	30	nS
$t_{RA}$	A port Rise Time	-	-	-	300	nS
$t_{FA}$	A port Fall Time	-	-	-	30	nS
$t_{PHL-A-B}$	Propagation Delay (Driving A)	-	-	-	20	nS
$t_{PLH-A-B}$		-	-	-	260	nS
$t_{PHL-B-A}$	Propagation Delay (Driving B)	-	-	-	20	nS
$t_{PLH-B-A}$		-	-	-	260	nS
$t_{PPSKEW}$	Part-to-Part Skew	-	-	-	1	nS
MDR	Maximum Data Rate	-	2	-	-	Mbps

## Test Circuits

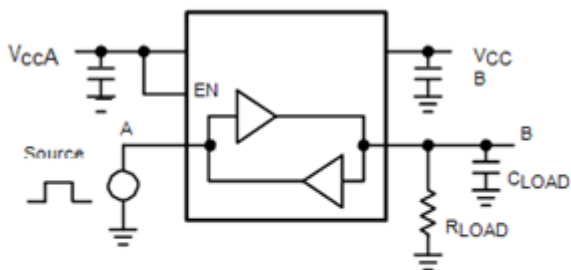


Figure 2. Rail-to-Rail Driving A

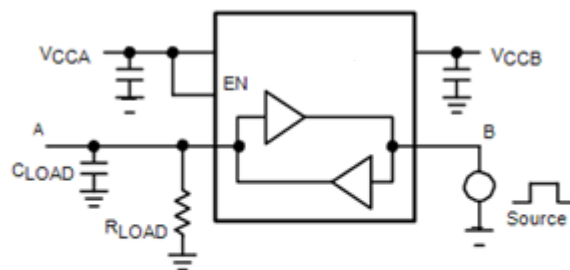


Figure 3. Rail-to-Rail Driving B

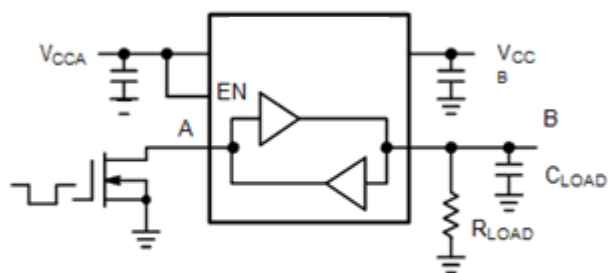


Figure 4. Open-Drain Driving A

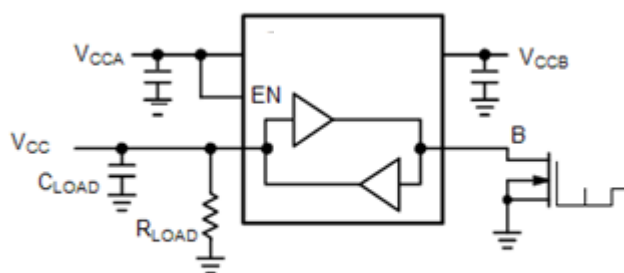
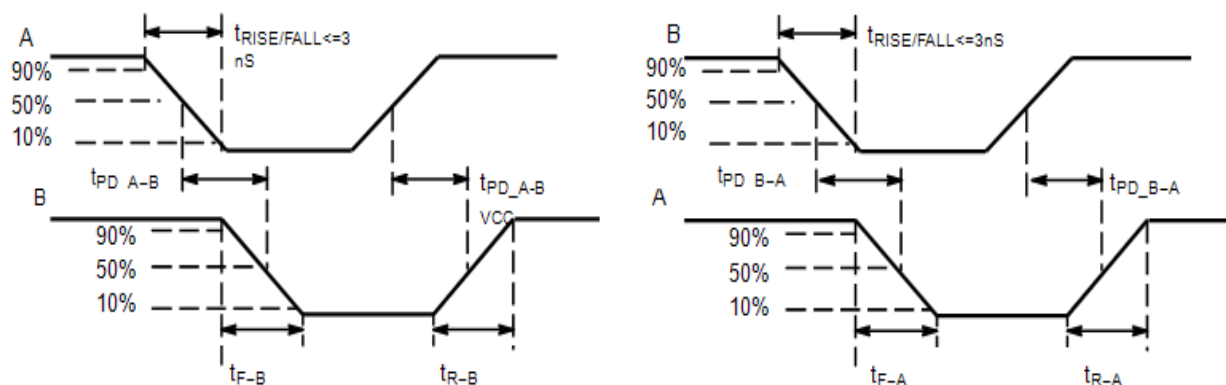
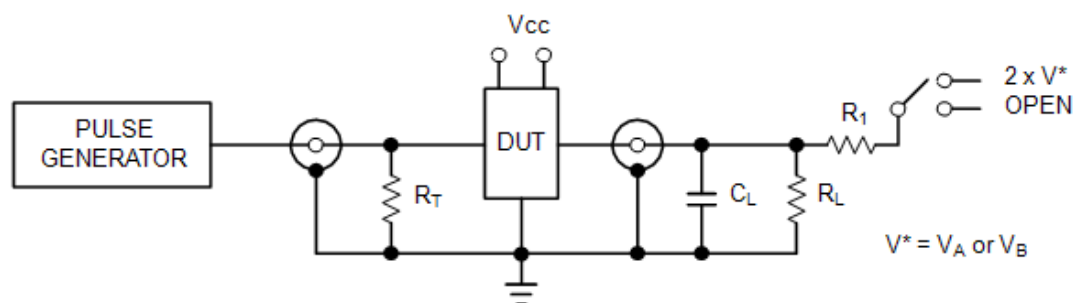


Figure 5. Open-Drain Driving B


**Figure 6. Definition of Timing Specification Parameters**


Test	Switch
$t_{PZH}$ , $t_{PHZ}$	Open
$t_{PZL}$ , $t_{PLZ}$	$2 \times V^*$

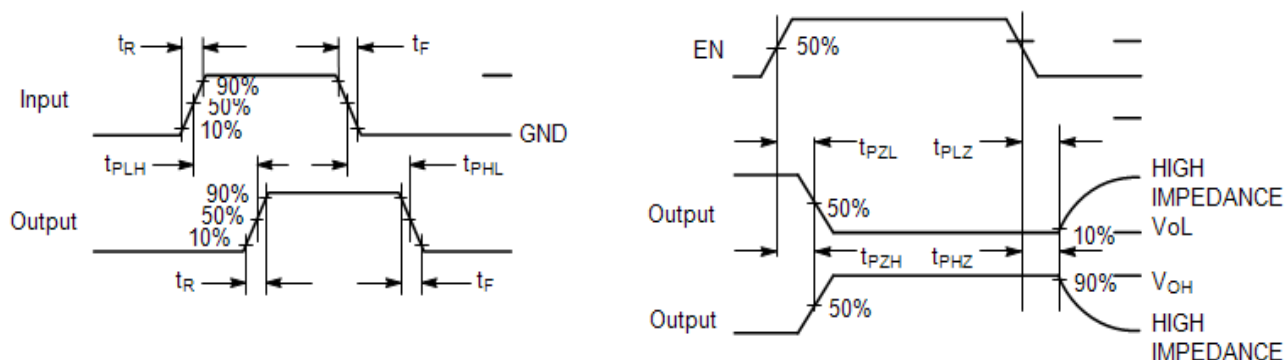
$C_L = 15 \text{ pF}$  or equivalent (Includes jig and probe capacitance)

$R_L = R_1 = 50 \text{ k}\Omega$  or equivalent

$R_T = Z_{OUT}$  of pulse generator (typically  $50 \Omega$ )

$V^* = V_A$  or  $V_B$  for A or B measurements, respectively.

**Figure 7. Test Circuit for Enable/Disable Time Measurement**



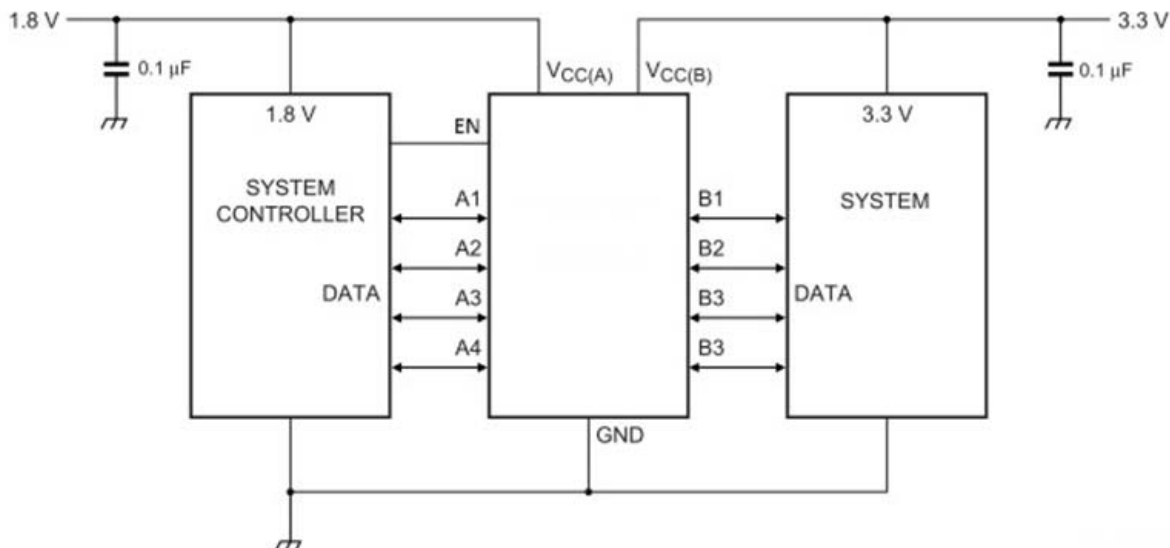
**Figure 8. Timing Definitions for Propagation Delays and Enable/Disable Measurement**

## Functional Description

The PI4ULS3V204 is a 4-bit configurable dual-supply bidirectional auto sensing translator that does not require a directional control pin. The A and B ports are designed to track two different power supply rails,  $V_{CCA}$  and  $V_{CCB}$  respectively. Both the  $V_{CCA}$  and  $V_{CCB}$  supply rails are configurable from 1.1 V to 3.6V. This allows voltage logic signals on the  $V_{CCA}$  side to be translated into lower, higher or equal value voltage logic signals on the  $V_{CCB}$  side, and vice-versa.

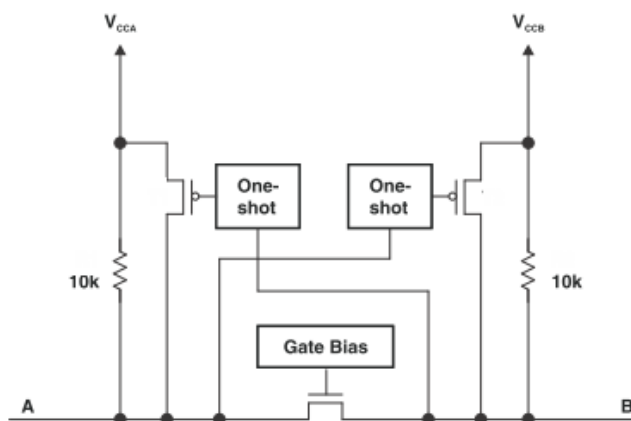
The translator has integrated 10 k $\Omega$  pull-up resistors on the I/O lines. The integrated pull-up resistors are used to pull-up the I/O lines to either  $V_{CCA}$  or  $V_{CCB}$ . The PI4ULS3V204 is an excellent match for open-drain applications such as the I<sup>2</sup>C communication bus.

## Application Information



## Level Translator Architecture

The PI4ULS3V204 auto sense translator provides bidirectional voltage level shifting to transfer data in multiple supply voltage systems. This device has two supply voltages,  $V_{CCA}$  and  $V_{CCB}$ , which set the logic levels on the input and output sides of the translator. When used to transfer data from A port to B port, input signals referenced to the  $V_{CCA}$  supply are translated to output signals with a logic level matched to  $V_{CCB}$ . In a similar manner, translation shifts input signals with a logic level compatible to  $V_{CCB}$  to an output signal matched to  $V_{CCA}$ . The PI4ULS3V204 consists of two bidirectional channels that independently determine the direction of the data flow without requiring a directional pin. The one-shot circuits are used to detect the rising or falling input signals. In addition, the one shots decrease the rise and fall time of the output signal for high-to-low and low-to-high transitions. Each input/output channel has an internal 10 k $\Omega$  pull. The magnitude of the pull-up resistors can be reduced by connecting external resistors in parallel to the internal 10 k $\Omega$  resistors.



## Input Driver Requirements

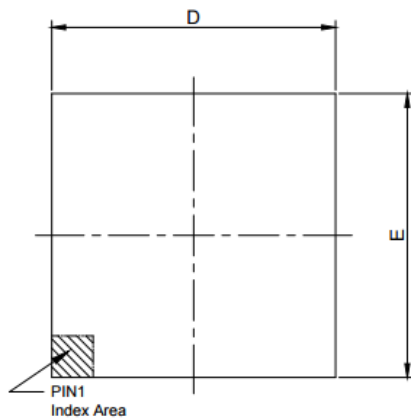
The rise ( $t_R$ ) and fall ( $t_F$ ) timing parameters of the open drain outputs depend on the magnitude of the pull-up resistors. In-addition, the propagation times ( $t_{PD}$ ), skew ( $t_{PSKEW}$ ) and maximum data rate depend on the impedance of the device that is connected to the translator. The timing parameters listed in the data sheet assume that the output impedance of the drivers connected to the translator is less than 50 k $\Omega$ .

## Enable Input (EN)

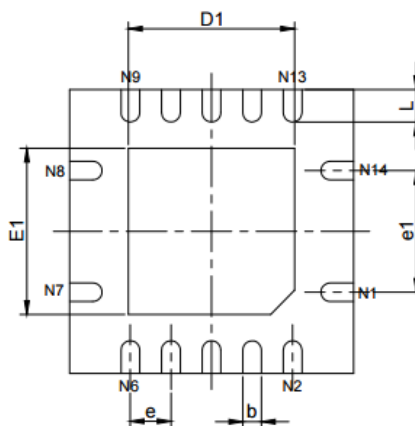
The PI4ULS3V204 has an Enable pin (EN) that provides tri-state operation at the I/O pins. Driving the Enable pin to a low logic level minimizes the power consumption of the device and drives the I/O VCCB and I/O VCCA pins to a high impedance state. Normal translation operation occurs when the EN pin is equal to a logic high signal. The EN pin is referenced to the VCCA supply and has overvoltage tolerant protection.

## Power Supply Guidelines

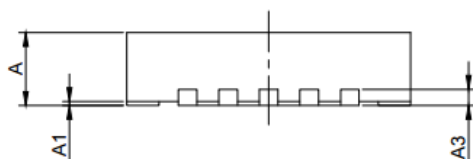
During normal operation, supply voltage VCCA can be greater than, less than or equal to VCCB. The sequencing of the power supplies will not damage the device during the power up operation. For optimal performance, 0.01 $\mu$ F to 0.1 $\mu$ F decoupling capacitors should be used on the VCCA and VCCB power supply pins. Ceramic capacitors are a good design choice to filter and bypass any noise signals on the voltage lines to the ground plane of the PCB. The noise immunity will be maximized by placing the capacitors as close as possible to the supply and ground pins, along with minimizing the PCB connection traces.

**PI4ULS3V204**
**Packaging Mechanical:**
**TQFN3.5x3.5-14L**


TOP VIEW



BOTTOM VIEW



SIDE VIEW

PKG. DIMENSIONS(MM)		
SYMBOL	Min	Max
A	0.80	0.90
A1	0.00	0.05
A3	0.20 REF	
D	3.42	3.58
E	3.42	3.58
D1	1.95	2.15
E1	1.95	2.15
b	0.20	0.30
e	0.50 TYP	
e1	1.50 TYP	
L	0.32	0.48

**Note:**  
 1. Ref: JEDEC MO-288B



DATE: 06/18/13

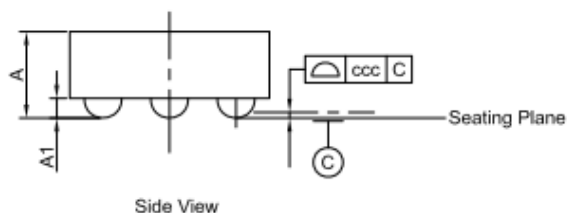
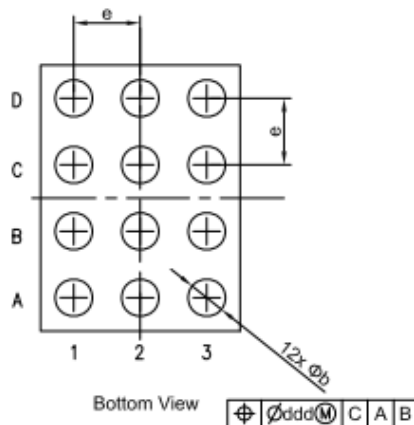
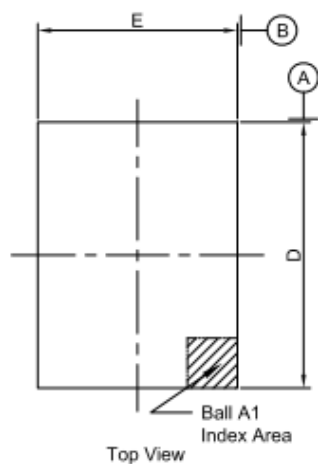
**DESCRIPTION:** 14-Pin, TQFN, 3.5x3.5

**PACKAGE CODE:** ZB (ZB14)

**DOCUMENT CONTROL #:** PD-2154

**REVISION:** --

13-0193

**PI4ULS3V204**
**CSP1.37x1.87-12 (GA)**


PKG. DIMENSIONS(MM)		
SYMBOL	Min	Max
A		0.625
A1	0.18	0.22
D	1.84	1.90
e	0.50 BSC	
E	1.34	1.40
b	0.24	0.28
ccc	0.05 TYP	
ddd	0.015 TYP	

Notes:  
 1. Ref: JEDEC MO-211C



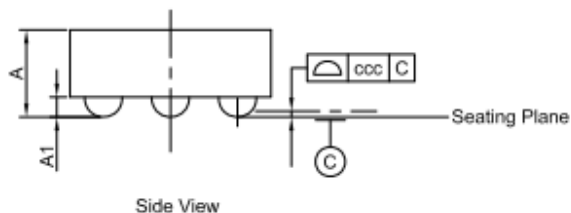
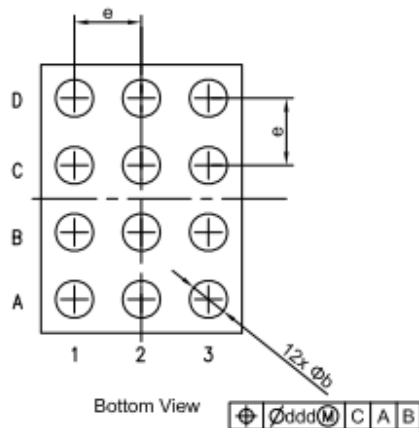
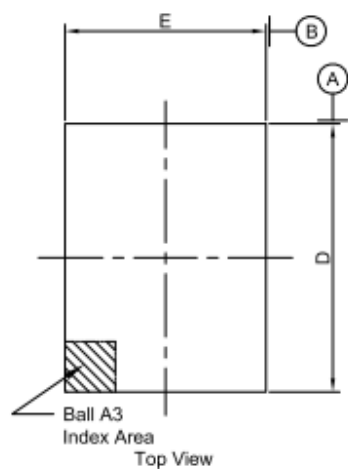
DATE: 05/18/17

DESCRIPTION: 12-Pin, CSP, 1.37X1.87, Wafer Level

PACKAGE CODE: GA (GA12)

DOCUMENT CONTROL#: PD-2156

REVISION: B

**PI4ULS3V204**
**CSP1.37x1.87-12 (GAA)**


PKG. DIMENSIONS(MM)		
SYMBOL	Min	Max
A		0.625
A1	0.18	0.22
D	1.84	1.90
e	0.50 BSC	
E	1.34	1.40
b	0.24	0.28
ccc	0.05 TYP	
ddd	0.015 TYP	

Notes:  
 1. Ref: JEDEC MO-211C



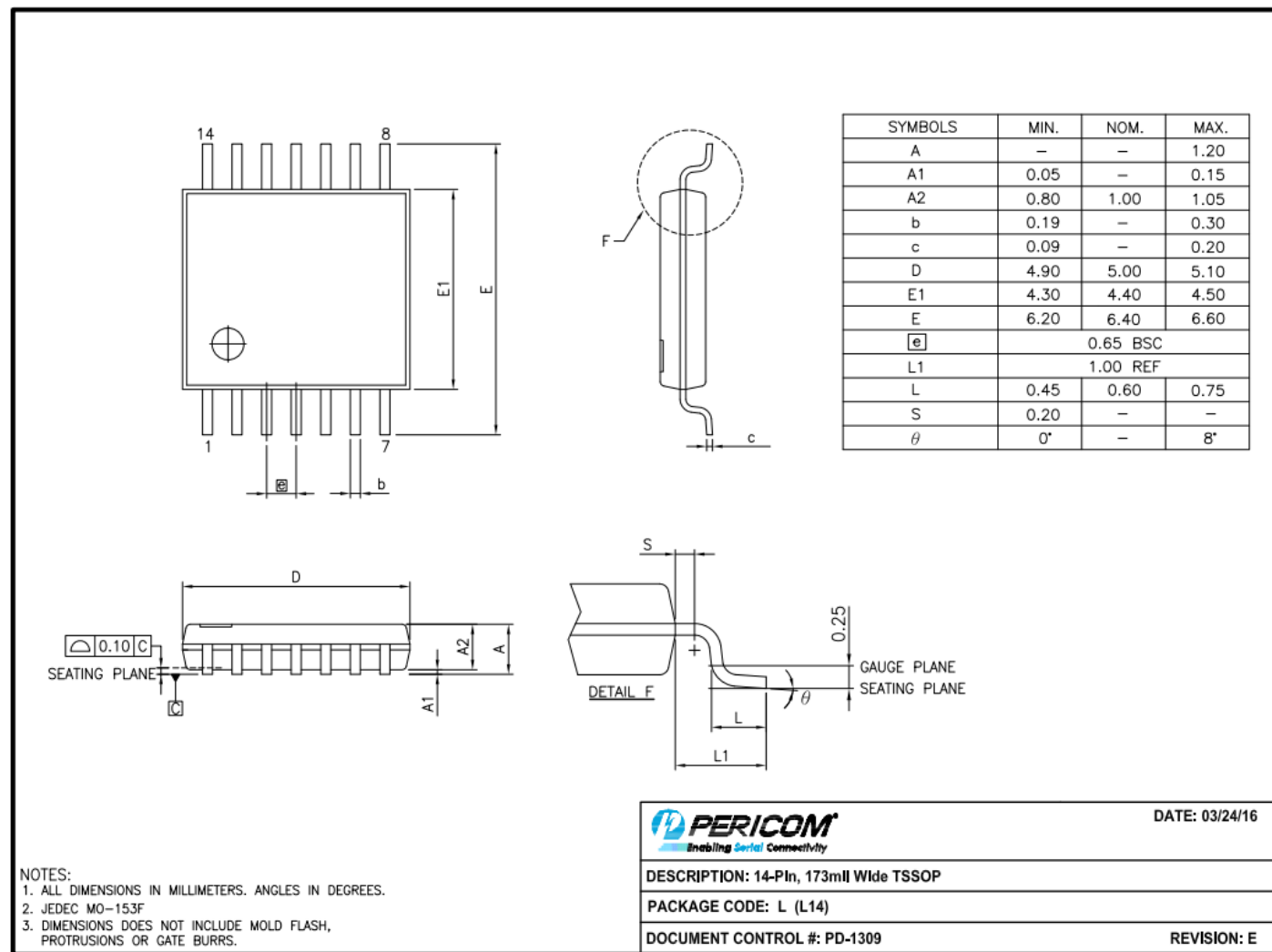
DATE: 05/18/17

DESCRIPTION: 12-Pin, CSP, 1.37X1.87, Wafer Level

PACKAGE CODE: GAA (GAA12)

DOCUMENT CONTROL#: PD-2229

REVISION: --

**PI4ULS3V204**
**TSSOP-14(L)**


For latest package info.

 please check: <http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/>
**Ordering Information**

Part Number	Package Code	Package
PI4ULS3V204LEX	L	14-Pin, 173 mil Wide (TSSOP)
PI4ULS3V204ZBEX	ZB	14-pin, 3.5x3.5 (TQFN)
PI4ULS3V204GAEX	GA	12-pin, 1.37x1.87 (CSP) Wafer Level
PI4ULS3V204GAAEX	GAA	12-pin, 1.37x1.87 (CSP) Wafer Level

**Notes:**

- Thermal characteristics can be found on the company web site at [www.diodes.com/design/support/packaging/](http://www.diodes.com/design/support/packaging/)
- E = Pb-free and Green
- X suffix = Tape/Reel

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